

### FEATURES

**Low noise figure: 1.8 dB**  
**P1dB output power: 14.5 dBm**  
**P<sub>SAT</sub> output power: 17.5 dBm**  
**High gain: 15 dB**  
**Output IP3: 29 dBm**  
**Supply voltage: V<sub>DD</sub> = 7 V at 70 mA**  
**50 Ω matched input/output (I/O)**  
**32-lead, 5 mm × 5 mm LFCSP package: 25 mm<sup>2</sup>**

### APPLICATIONS

**Test instrumentation**  
**High linearity microwave radios**  
**VSAT and SATCOM**  
**Military and space**

### GENERAL DESCRIPTION

The HMC1049LP5E is a GaAs MMIC low noise amplifier (LNA) that operates between 0.3 GHz and 20 GHz. This LNA provides 15 dB of small signal gain, 1.8 dB noise figure, and an IP3 output of 29 dBm, yet requires only 70 mA from a 7 V supply. The P1dB output power of 14.5 dBm enables the LNA to function as a local oscillator (LO) driver for balanced, I/Q, or

### FUNCTIONAL BLOCK DIAGRAM

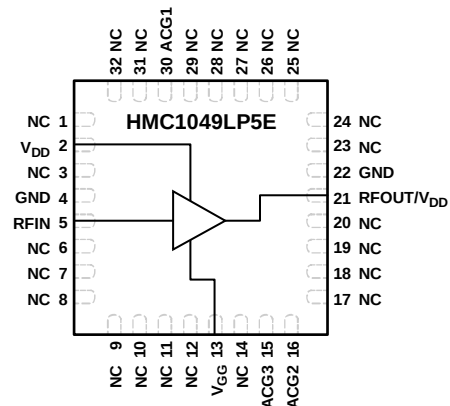


Figure 1.

image rejection mixers. V<sub>DD</sub> can also be applied to Pin 21, although Pin 21 requires a bias tee with V<sub>DD</sub> = 4 V. The HMC1049LP5E amplifier I/Os are internally matched to 50 Ω, and the device is supplied in a compact, leadless 5 mm × 5 mm LFCSP package.

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## REVISION HISTORY

### 5/2018—Rev. A to Rev. B

|                                                                |            |
|----------------------------------------------------------------|------------|
| Changed HMC1049 to HMC1049LP5E .....                           | Throughout |
| Changes to Features Section and General Description Section .. | 1          |
| Change to Figure 27 Caption and Figure 28 Caption .....        | 10         |
| Updated Outline Dimensions .....                               | 14         |
| Changes to Ordering Guide .....                                | 14         |

### 11/2014—Rev. 01.1213 to Rev. A

This Hittite Microwave Products data sheet has been reformatted to meet the styles and standards of Analog Devices, Inc.

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|                                                                  |           |
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| Updated Format .....                                             | Universal |
| Changes to General Description .....                             | 1         |
| Change to Table 2, Thermal Resistance Parameter Column .....     | 4         |
| Added Figure 2 .....                                             | 5         |
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| Moved Figure 3 to Figure 9 to Interface Schematics Section ..... | 6         |
| Change to Figure 8 and Figure 9 .....                            | 6         |
| Changes to Figure 36 .....                                       | 13        |
| Added Ordering Guide Section .....                               | 15        |

## SPECIFICATIONS

$T_A = 25^\circ\text{C}$ ,  $V_{DD} = 7\text{ V}$ ,  $I_{DD} = 70\text{ mA}$ <sup>1</sup>.

Table 1.

| Parameter                                       | Min  | Typ   | Max | Min | Typ   | Max | Min | Typ   | Max | Unit  |
|-------------------------------------------------|------|-------|-----|-----|-------|-----|-----|-------|-----|-------|
| FREQUENCY RANGE                                 | 0.3  |       | 1   | 1   |       | 14  | 14  |       | 20  | GHz   |
| GAIN                                            | 13.5 | 16.5  |     | 12  | 15    |     | 10  | 13    |     | dB    |
| Gain Variation Over Temperature                 |      | 0.006 |     |     | 0.019 |     |     | 0.017 |     | dB/°C |
| NOISE FIGURE                                    |      | 2.5   | 3.5 |     | 1.8   | 2.5 |     | 2.7   | 4.0 | dB    |
| RETURN LOSS                                     |      |       |     |     |       |     |     |       |     |       |
| Input                                           |      | 15    |     |     | 13    |     |     | 14    |     | dB    |
| Output                                          |      | 8     |     |     | 15    |     |     | 13    |     | dB    |
| OUTPUT                                          |      |       |     |     |       |     |     |       |     |       |
| Output Power for 1 dB Compression (P1dB)        |      | 15    |     |     | 14.5  |     |     | 13    |     | dBm   |
| Saturated ( $P_{SAT}$ )                         |      | 18    |     |     | 17.5  |     |     | 16    |     | dBm   |
| Output Third-Order Intercept (IP3) <sup>2</sup> |      | 31    |     |     | 29    |     |     | 26    |     | dBm   |
| TOTAL SUPPLY CURRENT                            |      | 70    |     |     | 70    |     |     | 70    |     | mA    |

<sup>1</sup> Adjust  $V_{GG}$  between  $-2\text{ V}$  to  $0\text{ V}$  to achieve  $I_{DD} = 70\text{ mA}$  typical.

<sup>2</sup> Measurement taken at  $P_{OUT}/\text{tone} = 8\text{ dBm}$ .

**ABSOLUTE MAXIMUM RATINGS**

Table 2.

| Parameter                                                                                             | Rating          |
|-------------------------------------------------------------------------------------------------------|-----------------|
| Drain Bias Voltage ( $V_{DD}$ )                                                                       | 10 V            |
| Drain Bias Voltage (RF Out/ $V_{DD}$ )                                                                | 7 V             |
| RF Input Power                                                                                        | 18 dBm          |
| Gate Bias Voltage, $V_{GG}$                                                                           | –2 V to +0.2 V  |
| Channel Temperature                                                                                   | 175°C           |
| Continuous $P_{DISS}$ ( $T = 85^{\circ}\text{C}$ )<br>(Derate 37.1 mW/ $^{\circ}\text{C}$ Above 85°C) | 3.34 W          |
| Thermal Resistance (Channel to Ground Paddle)                                                         | 26.9°C/W        |
| Temperature                                                                                           |                 |
| Storage Temperature                                                                                   | –65°C to +150°C |
| Operating Temperature                                                                                 | –40°C to +85°C  |
| ESD Sensitivity (HBM)                                                                                 | Class 1A        |

Stresses at or above those listed under Absolute Maximum Ratings may cause permanent damage to the product. This is a stress rating only; functional operation of the product at these or any other conditions above those indicated in the operational section of this specification is not implied. Operation beyond the maximum operating conditions for extended periods may affect product reliability.

Table 3. Typical Supply Current vs.  $V_{DD}$ 

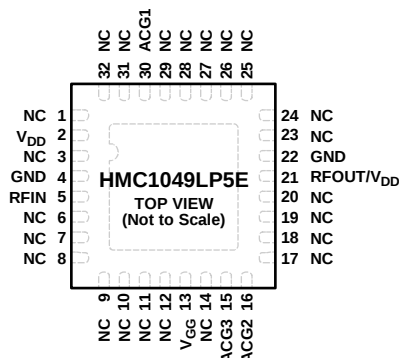
| $V_{DD}$ (V) | $I_{DD}^1$ (mA) |
|--------------|-----------------|
| 5            | 70              |
| 6            | 70              |
| 7            | 70              |

<sup>1</sup> Adjust  $V_{GG}$  to achieve  $I_{DD} = 70$  mA.

**ESD CAUTION**

**ESD (electrostatic discharge) sensitive device.** Charged devices and circuit boards can discharge without detection. Although this product features patented or proprietary protection circuitry, damage may occur on devices subjected to high energy ESD. Therefore, proper ESD precautions should be taken to avoid performance degradation or loss of functionality.

## PIN CONFIGURATION AND FUNCTION DESCRIPTIONS



## NOTES

1. NC = NO CONNECT. THESE PINS ARE NOT CONNECTED INTERNALLY; HOWEVER, ALL DATA WAS MEASURED WITH THESE PINS CONNECTED TO RF/DC GROUND EXTERNALLY.
2. EXPOSED PAD. THE EXPOSED GROUND PADDLE MUST BE CONNECTED TO RF/DC GROUND.

16798-004

Figure 2. Pin Configuration Diagram

Table 4. Pin Function Descriptions

| Pin No.                                       | Mnemonic              | Description <sup>1</sup>                                                                                                                                                                                       |
|-----------------------------------------------|-----------------------|----------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------------|
| 1, 3, 6 to 12, 14, 17 to 20, 23 to 29, 31, 32 | NC                    | No Connect. These pins are not connected internally; however, all data was measured with these pins connected to RF/dc ground externally (see the Typical Performance Characteristics section for data plots). |
| 5                                             | RFIN                  | RF Input. This pin is dc-coupled and matched to 50 $\Omega$ .                                                                                                                                                  |
| 2                                             | V <sub>DD</sub>       | Power Supply Voltage for the Amplifier. External bypass capacitors (100 pF and 0.01 $\mu$ F) are required.                                                                                                     |
| 30                                            | ACG1                  | Low Frequency Termination. An external bypass capacitor of 100 pF is required.                                                                                                                                 |
| 21                                            | RFOUT/V <sub>DD</sub> | RF Output/Alternate Power Supply Voltage for the Amplifier. An external bias tee is required when used as alternative V <sub>DD</sub> . This pin is dc-coupled and matched to 50 $\Omega$ .                    |
| 15, 16                                        | ACG2, ACG3            | Low Frequency Termination. External bypass capacitors of 100 pF are required.                                                                                                                                  |
| 13                                            | V <sub>GG</sub>       | Gate Control for Amplifier. Adjust the voltage to achieve I <sub>DD</sub> = 70 mA. External bypass capacitors of 100 pF, 0.01 $\mu$ F, and 4.7 $\mu$ F are required.                                           |
| 4, 22                                         | GND                   | Ground. Connect Pin 4 and Pin 22 to RF/dc ground.                                                                                                                                                              |
| 0                                             | EP                    | Exposed Pad. The exposed ground paddle must be connected to RF/dc ground.                                                                                                                                      |

<sup>1</sup> See the Interface Schematics section for pin interfaces.

INTERFACE SCHEMATICS

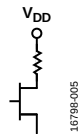


Figure 3. V<sub>DD</sub> Interface



Figure 4. GND Interface

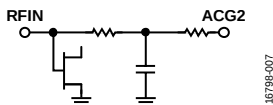


Figure 5. RFIN Interface

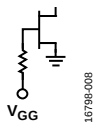


Figure 6. V<sub>GG</sub> Interface

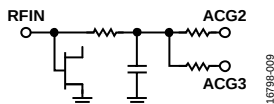


Figure 7. ACG2 and ACG3 Interface

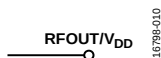


Figure 8. RFOUT/V<sub>DD</sub> Interface

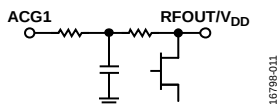


Figure 9. ACG1 Interface

## TYPICAL PERFORMANCE CHARACTERISTICS

Data taken with  $V_{DD}$  applied to Pin 2,  $V_{DD} = 7$  V.

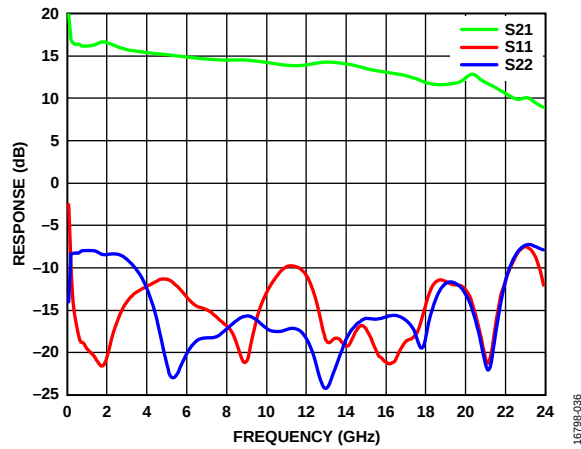


Figure 10. Broadband Gain and Return Loss

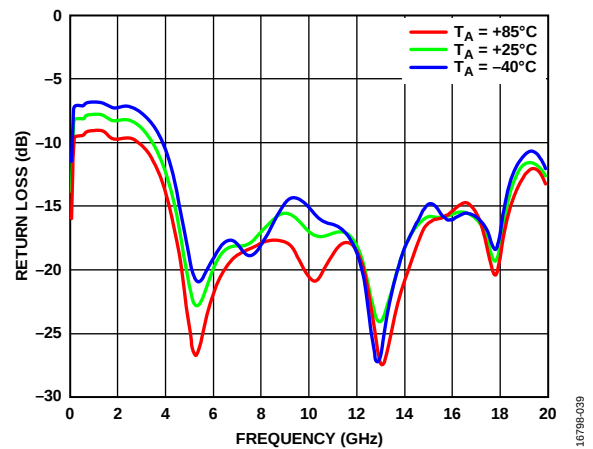


Figure 13. Output Return Loss vs. Temperature

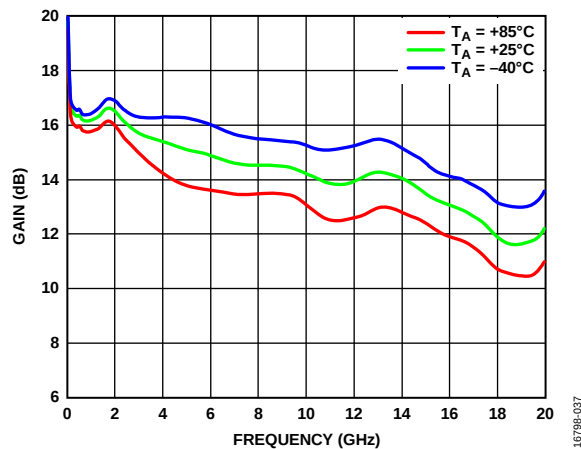


Figure 11. Gain vs. Temperature

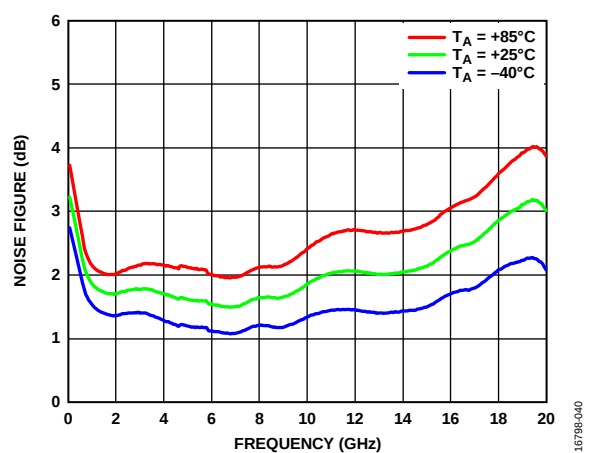


Figure 14. Noise Figure vs. Temperature

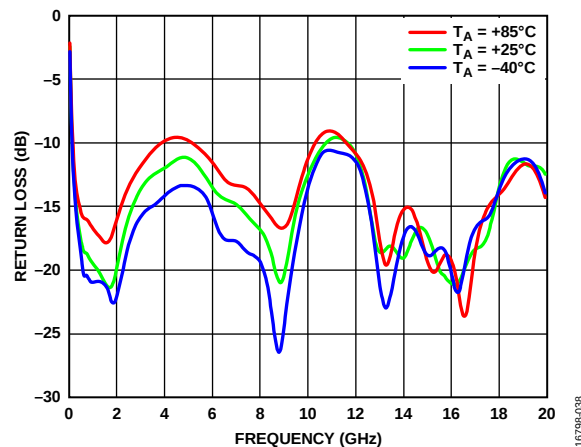


Figure 12. Input Return Loss vs. Temperature

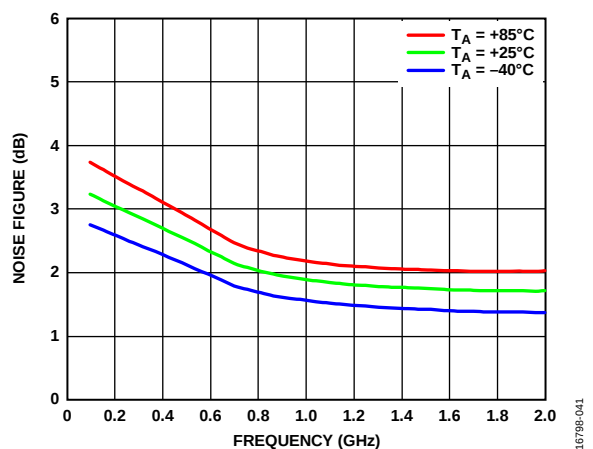


Figure 15. Noise Figure vs. Temperature, Low Frequency

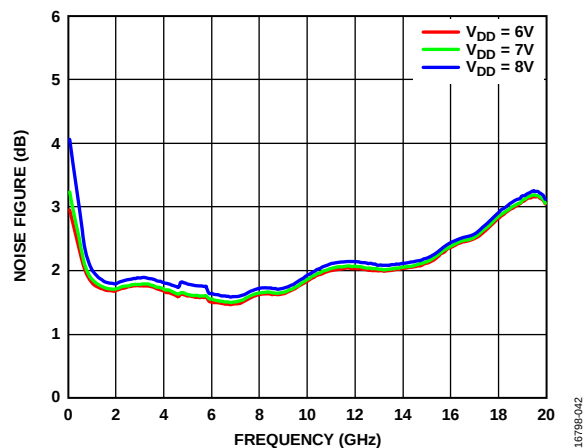
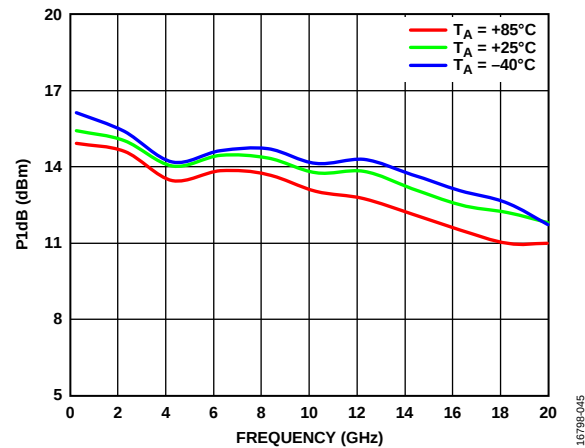
Figure 16. Noise Figure vs.  $V_{DD}$ 

Figure 19. P1dB vs. Temperature

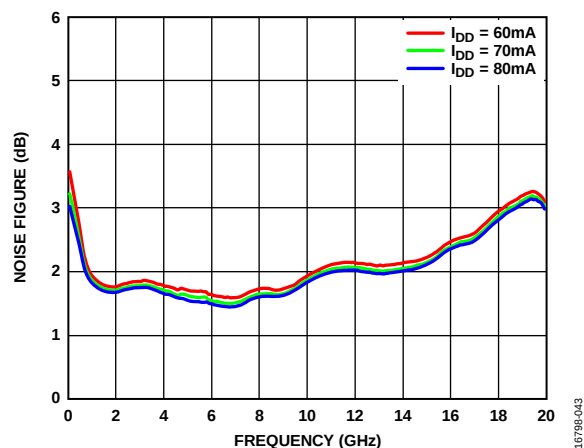
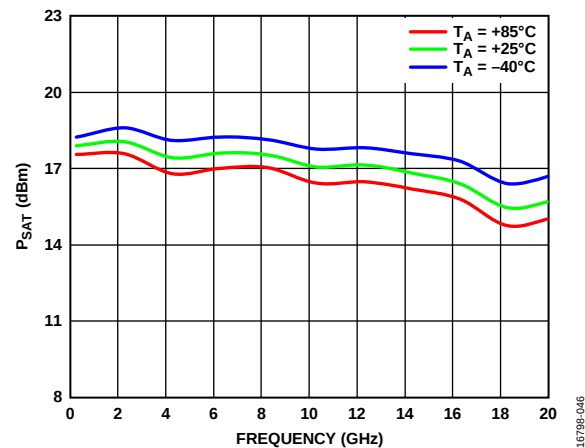
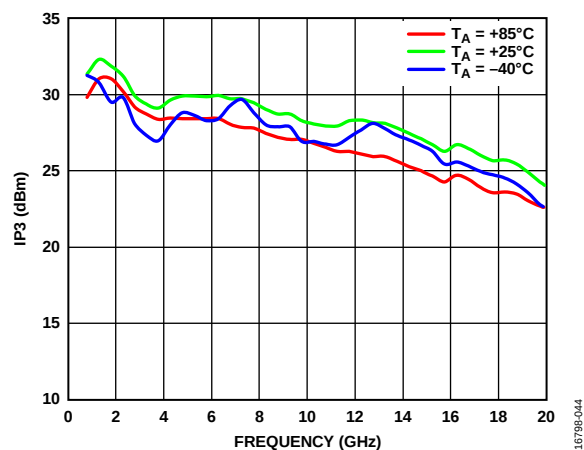
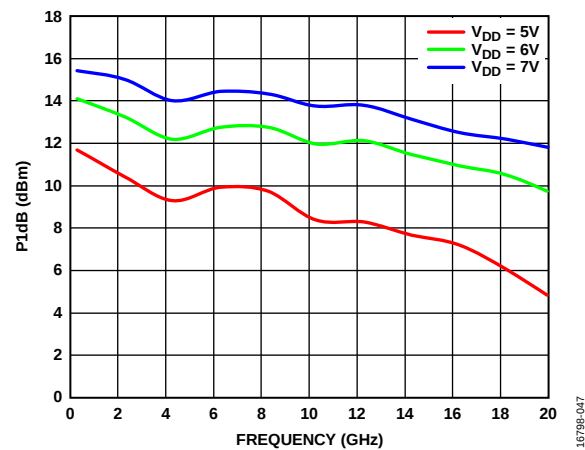
Figure 17. Noise Figure vs.  $I_{DD}$ Figure 20.  $P_{SAT}$  vs. Temperature

Figure 18. Output IP3 vs. Temperature

Figure 21. P1dB vs.  $V_{DD}$

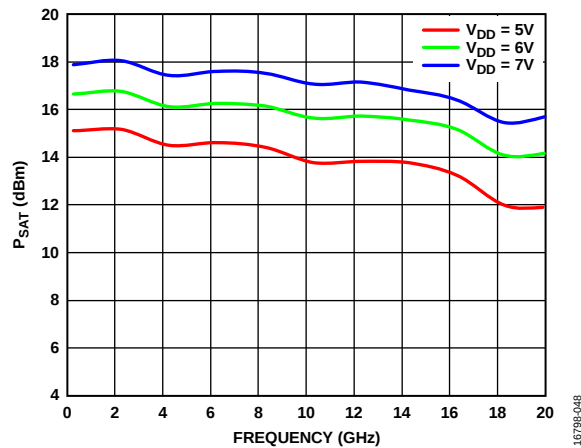


Figure 22.  $P_{SAT}$  vs.  $V_{DD}$

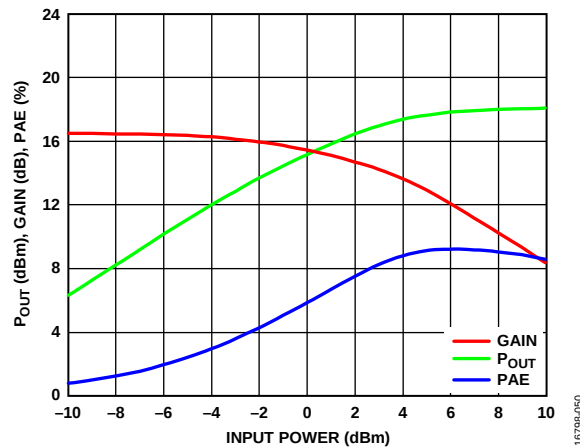


Figure 24. Power Compression at 2 GHz

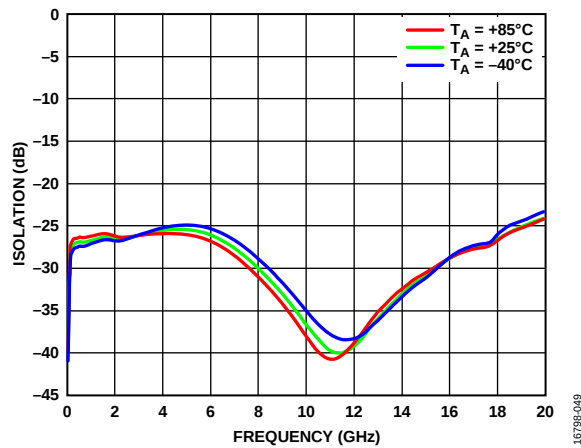


Figure 23. Reverse Isolation vs. Temperature

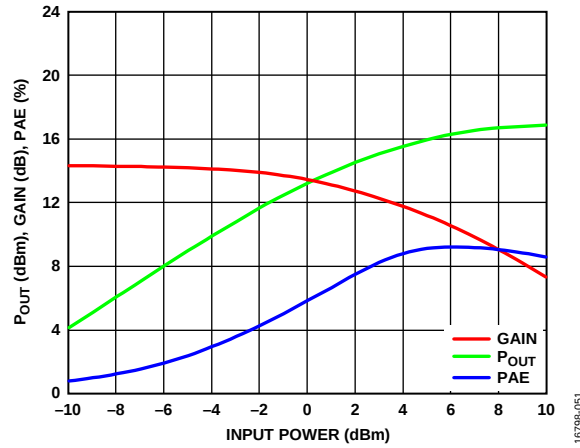


Figure 25. Power Compression at 10 GHz

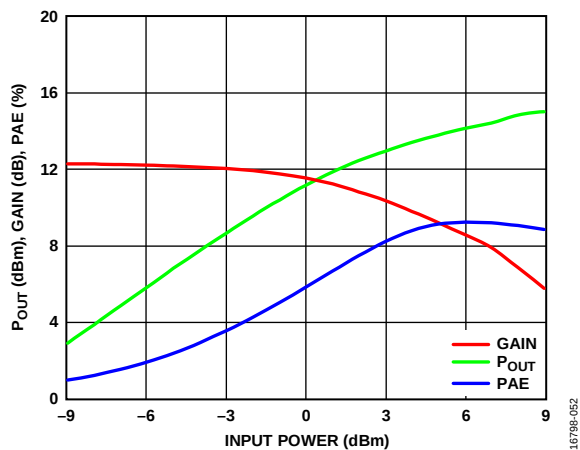
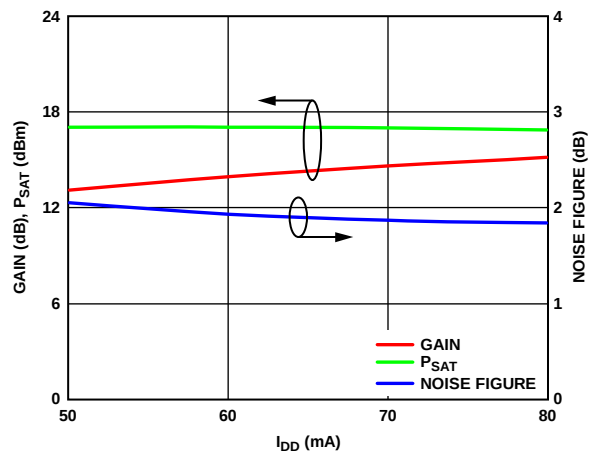
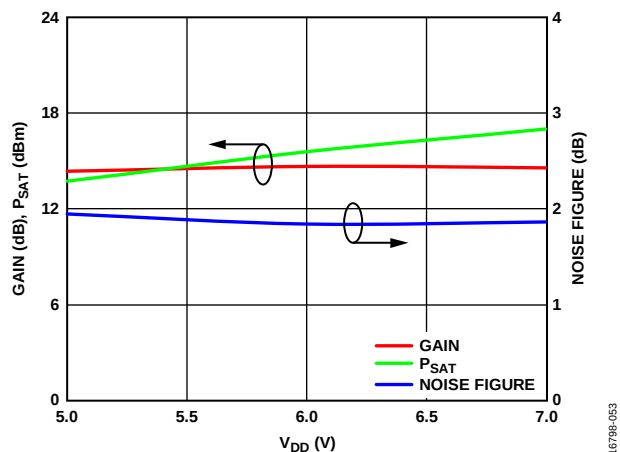


Figure 26. Power Compression at 18 GHz

Figure 28. Gain, P<sub>SAT</sub>, and Noise Figure vs. I<sub>DD</sub> at 12 GHzFigure 27. Gain, P<sub>SAT</sub>, and Noise Figure vs. V<sub>DD</sub> at 12 GHz

Data taken with  $V_{DD}$  applied to the bias tee at Pin 21.

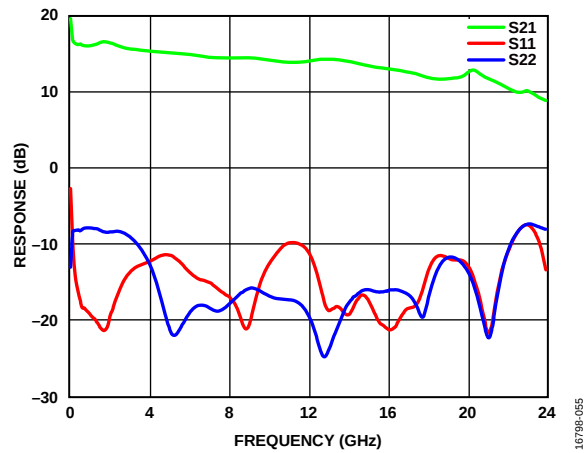


Figure 29. Broadband Gain and Return Loss,  $V_{DD} = 4$  V, Supply to Bias Tee

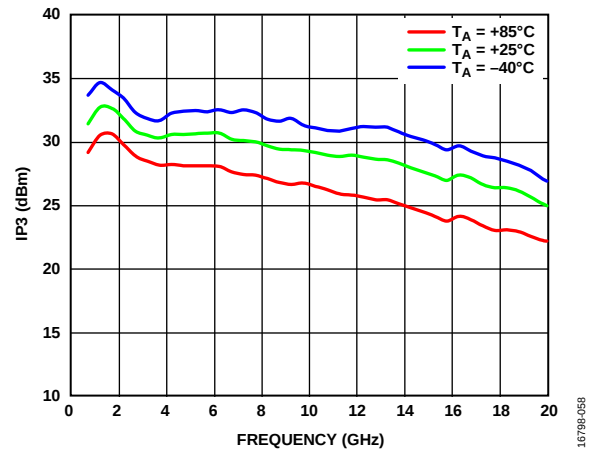


Figure 32. Output IP3 vs. Temperature,  $V_{DD} = 4$  V, Supply to Bias Tee

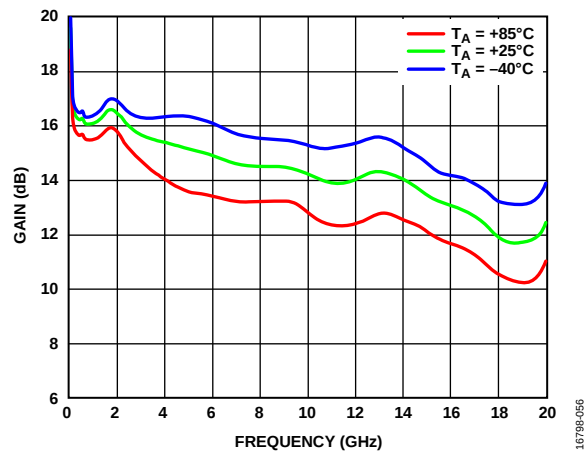


Figure 30. Gain vs. Temperature,  $V_{DD} = 4$  V, Supply to Bias Tee

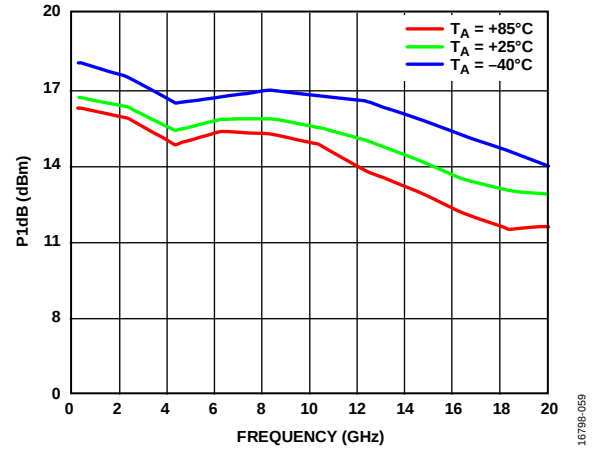


Figure 33. P1dB vs. Temperature,  $V_{DD} = 4$  V, Supply to Bias Tee

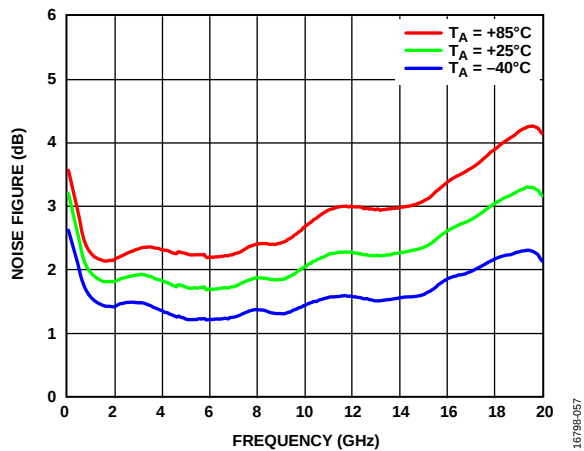


Figure 31. Noise Figure vs. Temperature,  $V_{DD} = 4$  V, Supply to Bias Tee

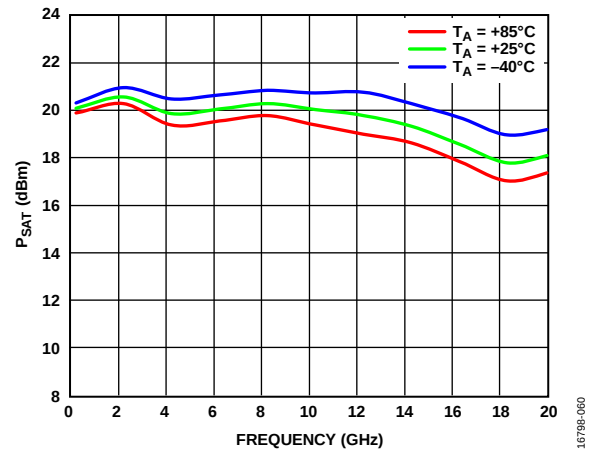


Figure 34.  $P_{SAT}$  vs. Temperature,  $V_{DD} = 4$  V, Supply to Bias Tee

## EVALUATION PRINTED CIRCUIT BOARD

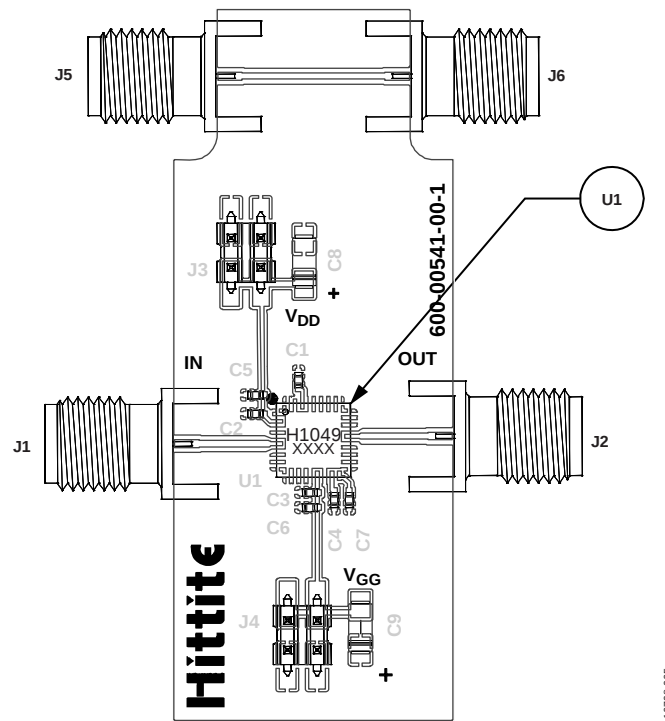


Figure 35. Evaluation Board Layout

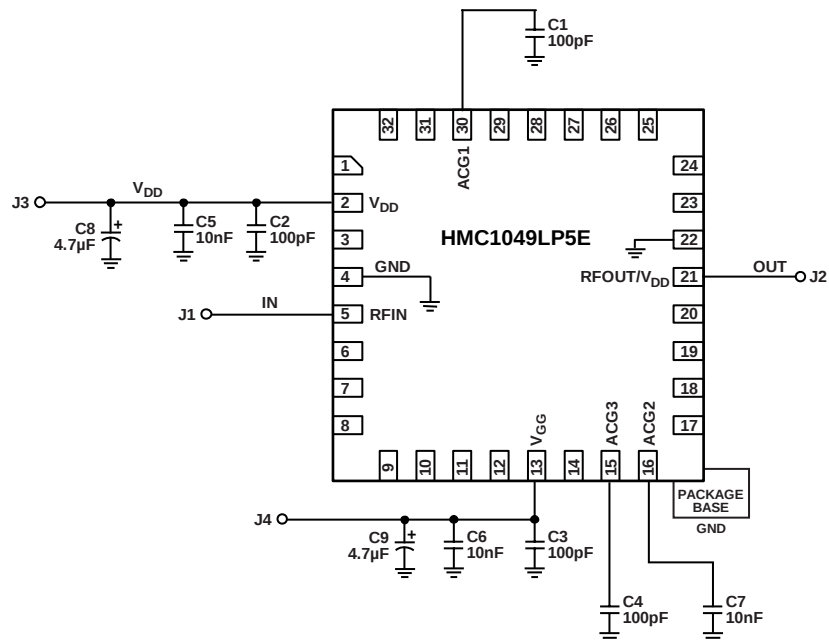


Figure 36. Evaluation Board Schematic

**Table 5. List of Materials for Evaluation PCB**

| Item             | Description                      |
|------------------|----------------------------------|
| J1, J2, J5, J6   | PCB mount SMA RF connector       |
| J3, J4           | DC pins                          |
| C1 to C4         | 100 pF capacitor, 0402 package   |
| C5 to C7         | 10000 pF capacitor, 0402 package |
| C8, C9           | 4.7 $\mu$ F capacitor, tantalum  |
| U1               | HMC1049LP5E                      |
| PCB <sup>1</sup> | 600-00541-00-1 evaluation PCB    |

<sup>1</sup> Circuit board material: Rogers 4350 or Arlon 25FR.

The circuit board used in the application should use RF circuit design techniques. Signal lines should have 50  $\Omega$  impedance; connect the package ground leads and exposed paddle directly to the ground plane. Use a sufficient number of via holes to connect the top and bottom ground planes. The evaluation circuit board shown is available from Analog Devices, Inc., upon request.

## PACKAGING AND ORDERING INFORMATION

## OUTLINE DIMENSIONS

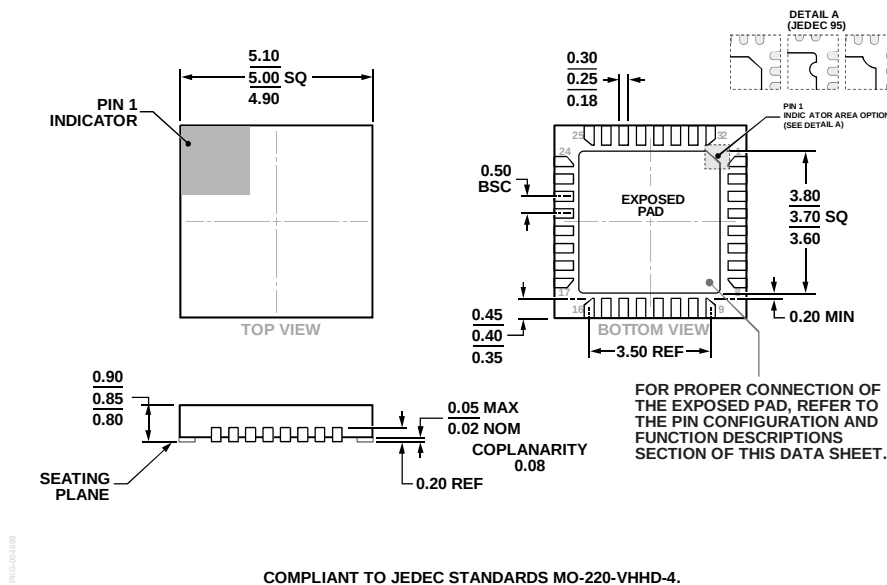


Figure 37. 32-Lead Lead Frame Chip Scale Package [LFCSP]  
 5 mm × 5 mm and 0.85 mm Package Height  
 (HCP-32-1)  
 Dimensions shown in millimeters

## ORDERING GUIDE

| Model <sup>1</sup> | Temperature Range | Lead Finish   | Moisture Sensitivity Level (MSL) Rating <sup>2</sup> | Package Description                | Ordering Quantity | Package Option |
|--------------------|-------------------|---------------|------------------------------------------------------|------------------------------------|-------------------|----------------|
| HMC1049LP5E        | –40°C to +85°C    | 100% matte Sn | MSL1                                                 | 32-Lead LFCSP                      | 500               | HCP-32-1       |
| HMC1049LP5ETR      | –40°C to +85°C    | 100% matte Sn | MSL1                                                 | 32-Lead LFCSP,<br>7" Tape and Reel |                   | HCP-32-1       |
| EVAL01-HMC1049LP5  |                   |               |                                                      | Evaluation Board                   |                   |                |

<sup>1</sup> All models are RoHS Compliant Parts.

<sup>2</sup> MSL1 rating indicates a maximum peak reflow temperature of 260°C.

## Данный компонент на территории Российской Федерации

**Вы можете приобрести в компании MosChip.**

Для оперативного оформления запроса Вам необходимо перейти по данной ссылке:

<http://moschip.ru/get-element>

Вы можете разместить у нас заказ для любого Вашего проекта, будь то серийное производство или разработка единичного прибора.

В нашем ассортименте представлены ведущие мировые производители активных и пассивных электронных компонентов.

Нашей специализацией является поставка электронной компонентной базы двойного назначения, продукции таких производителей как XILINX, Intel (ex.ALTERA), Vicor, Microchip, Texas Instruments, Analog Devices, Mini-Circuits, Amphenol, Glenair.

Сотрудничество с глобальными дистрибьюторами электронных компонентов, предоставляет возможность заказывать и получать с международных складов практически любой перечень компонентов в оптимальные для Вас сроки.

На всех этапах разработки и производства наши партнеры могут получить квалифицированную поддержку опытных инженеров.

Система менеджмента качества компании отвечает требованиям в соответствии с ГОСТ Р ИСО 9001, ГОСТ РВ 0015-002 и ЭС РД 009

### Офис по работе с юридическими лицами:

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